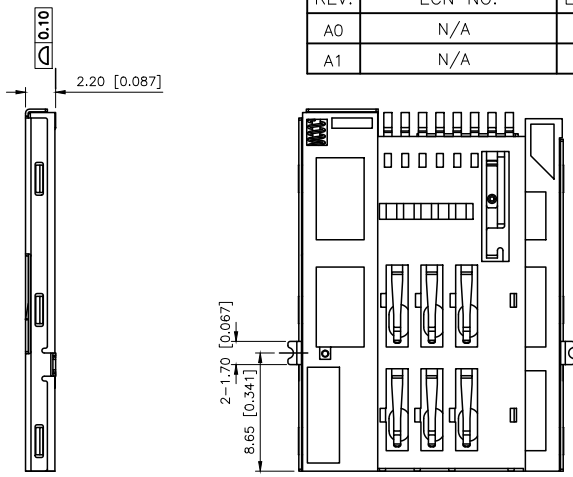
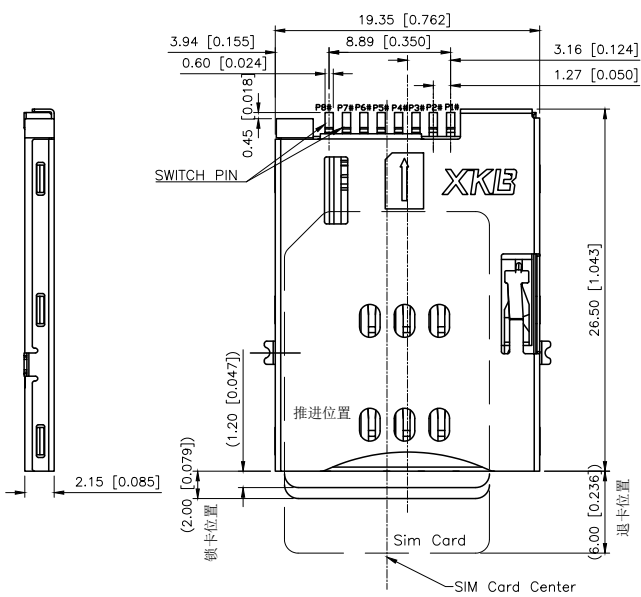
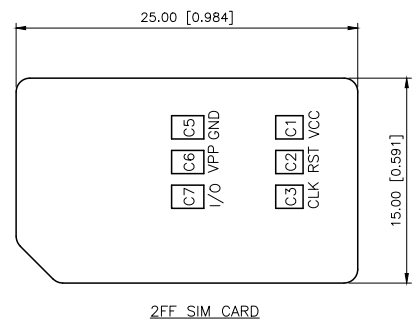
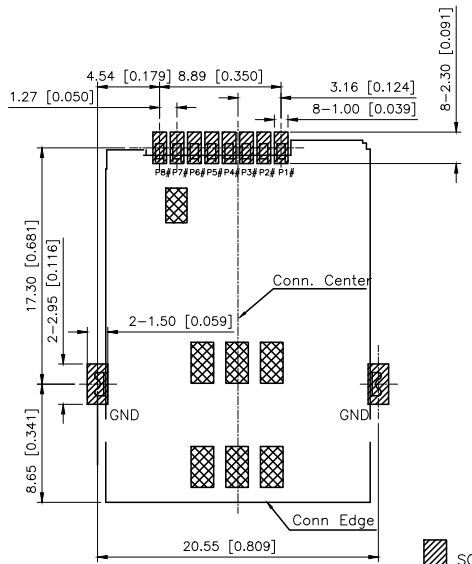
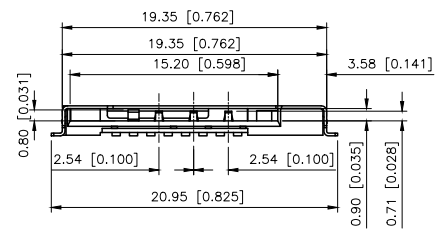


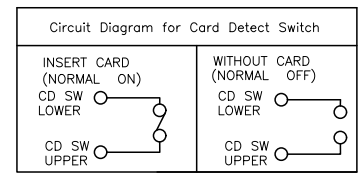
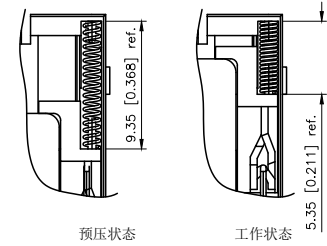
REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.05.09	阿树



- 1) MATERIAL:
 HOUSING: LCP UL 94V-0
 TERMINAL: COPPER ALLOY ,T=0.15
 SHELL: SUS,T=0.15
 MYLAR: POLYESTER
- 2) FINISH :
 TERMINAL:GOLD FLASH PLATED ON CONTACT AREA;
 GOLD FLASH PLATING ON SOLDER TAILS, WITH
 ENTIRE CONTACT UNDERPLATED 50u"Min,NICKEL
 SHELL: 50u"Min. NICKEL UNDERPLATED OVERALL ,
 GOLD FLASH PLATED ON SOLDER TAILS
- 3)INFRARED REFLOW SOLDERING: 10sec. Min. at 260±3°



PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET



AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERANCES	



DESIGN	阿树	VIEW:		MODEL TYPE:	SIM CARD CONN
CHECKED		UNIT:	mm/in	PART NO.:	XKSIM-115
APPROVED		SIZE:	A4	DWG NO.:	

SCALE	PAGE	REVISION
N/A	1/1	A1